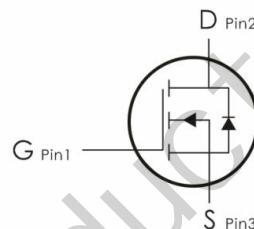


Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge : $Q_g=60\text{nC}$ (Typ.).
- $\text{BV}_{\text{DSS}}=100\text{V}, I_{\text{D}}=100\text{A}$
- $R_{\text{DS}(\text{on})} : 0.012\Omega$ (Max) @ $V_{\text{G}}=10\text{V}$
- 100% Avalanche Tested


Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Maximum	Unit
V_{DSS}	Drain-to-Source Voltage	100	V
V_{GSS}	Gate-to-Source Voltage	± 25	V
I_{D}^3	Continuous Drain Current	$T_C=25^\circ\text{C}$	100
		$T_C=100^\circ\text{C}$	51
I_{DP}^4	Pulsed Drain Current	$T_C=25^\circ\text{C}$	219
I_{AS}^5	Avalanche Current	30	
E_{AS}^5	Avalanche energy	225	mJ
PD	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	166
		$T_C=100^\circ\text{C}$	83
T_J, T_{STG}	Junction & Storage Temperature Range	-55~175	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta\text{jc}}$	Thermal Resistance-Junction to Case	0.9	$^\circ\text{C/W}$
$R_{\theta\text{ja}}$	Thermal Resistance-Junction to Ambient	62.5	

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	100	—	—	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=80\text{V}, V_{GS}=0\text{V}$	—	—	1	uA
		$T_J=125^\circ\text{C}$	—	—	20	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	3	4	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 25\text{V}, V_{DS}=0\text{V}$	—	—	± 100	nA
$R_{DS(on)}^1$	Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=50\text{A}$	—	10	12	mΩ
		—	—	—	—	
Diode Characteristics						
V_{SD}^1	Diode Forward Voltage	$I_{SD}=50\text{A}, V_{GS}=0\text{V}$	—	—	1.3	V
I_S^3	Diode Continuous Forward Current	—	—	—	100	A
t_{rr}	Reverse Recovery Time	$I_F=50\text{A},$ $dI/dt=100\text{A}/\mu\text{s}$	—	46	—	nS
Q_{rr}	Reverse Recovery Charge		—	86	—	nC
Dynamic Characteristics ²						
R_G	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V},$ Frequency=1MHz	—	1.2	—	Ω
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}$ Frequency=1MHz	—	2946	—	pF
C_{oss}	Output Capacitance		—	339	—	
C_{rss}	Reverse Transfer Capacitance		—	179	—	
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=50\text{V}, I_D=30\text{A},$ $V_{GS}=10\text{V}, R_G=6.8\Omega$	—	15	—	nS
t_r	Rise Time		—	108	—	
$t_{d(off)}$	Turn-Off Delay Time		—	51	—	
t_f	Fall Time		—	59	—	
Gate Charge Characteristics ²						
Q_g	Total Gate Charge	$V_{DS}=50\text{V}, V_{GS}=10\text{V}$ $I_D=30\text{A}$	—	60	—	nC
Q_{gs}	Gate-to-Source Charge		—	13.7	—	
Q_{gd}	Gate-to-Drain Charge		—	22.8	—	

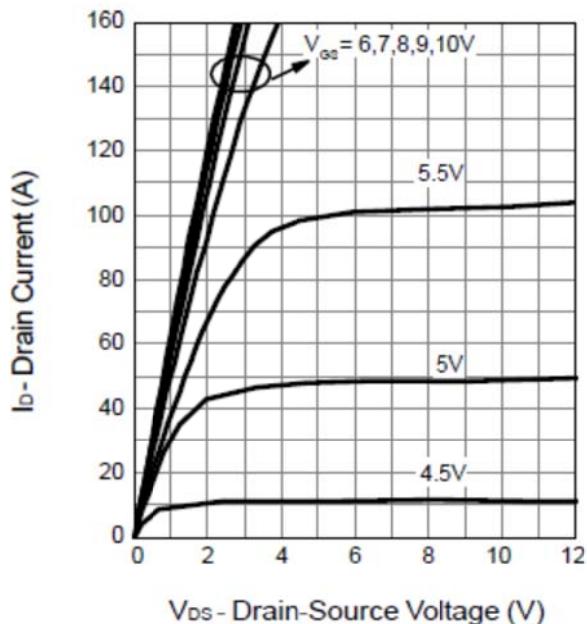
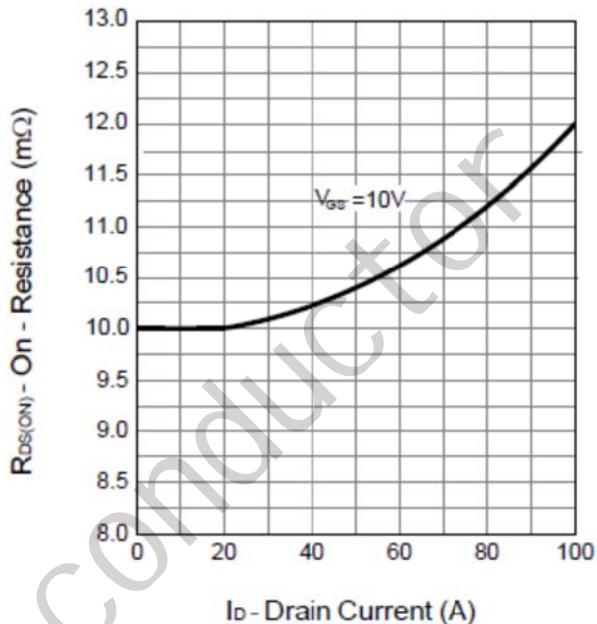
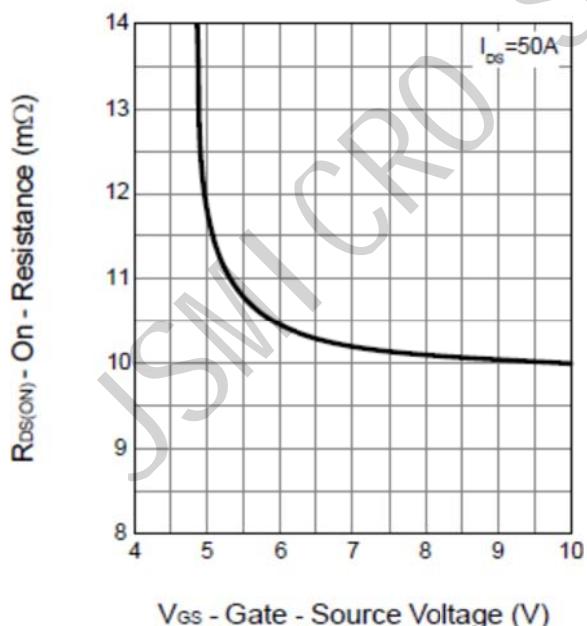
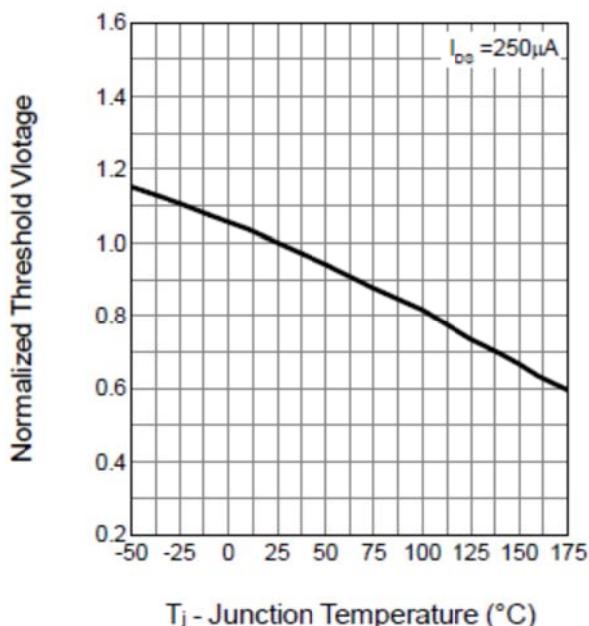
Note: 1: Pulse test; pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

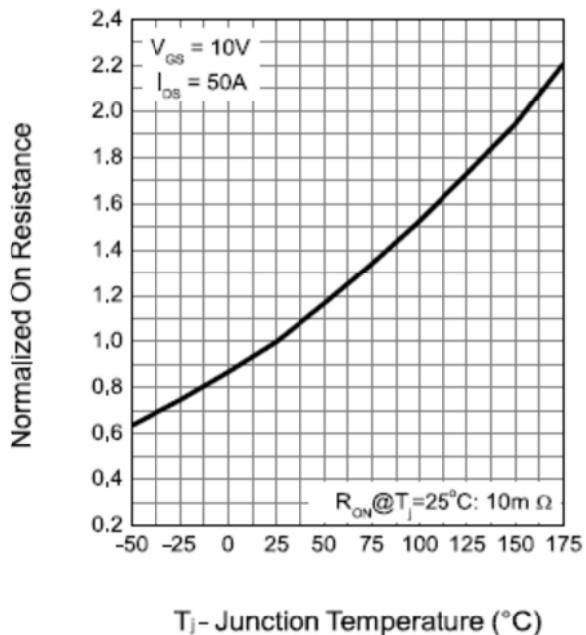
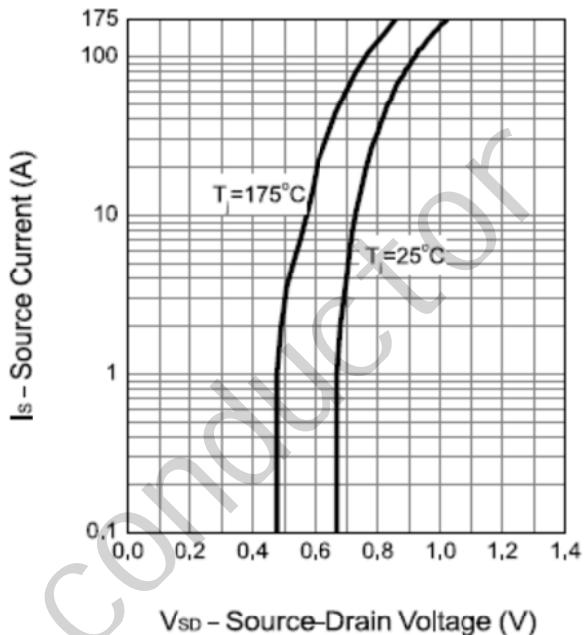
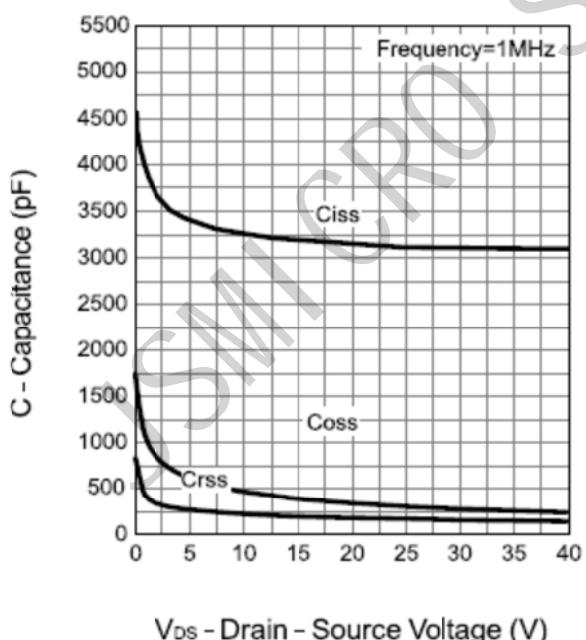
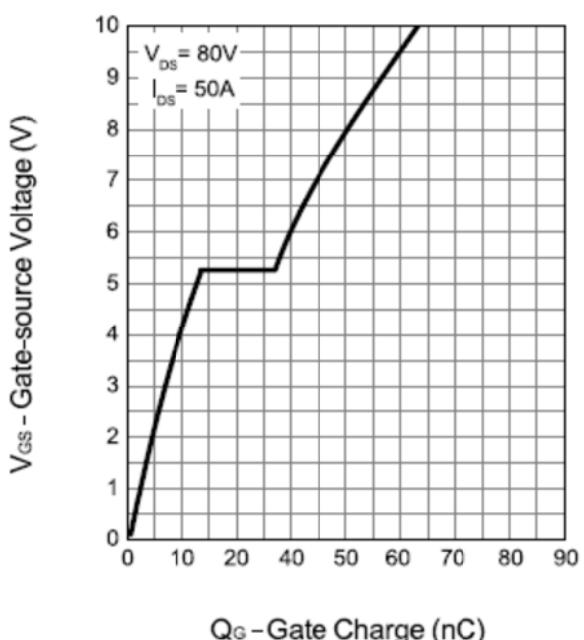
2: Guaranteed by design, not subject to production testing.

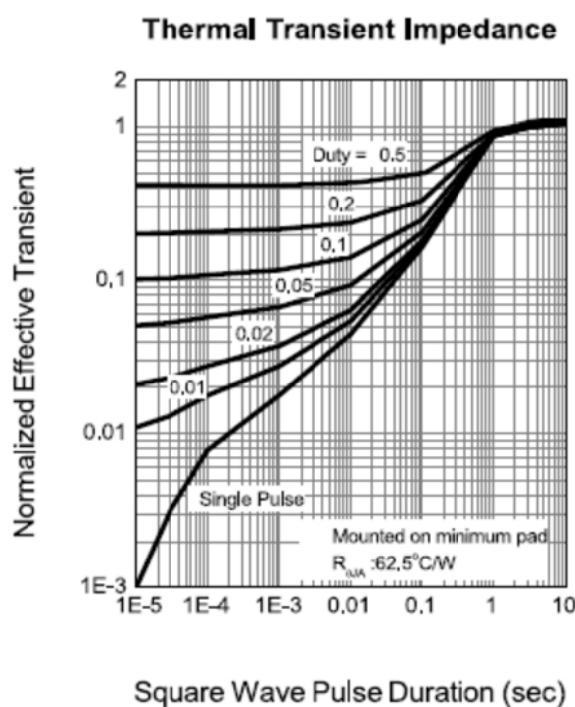
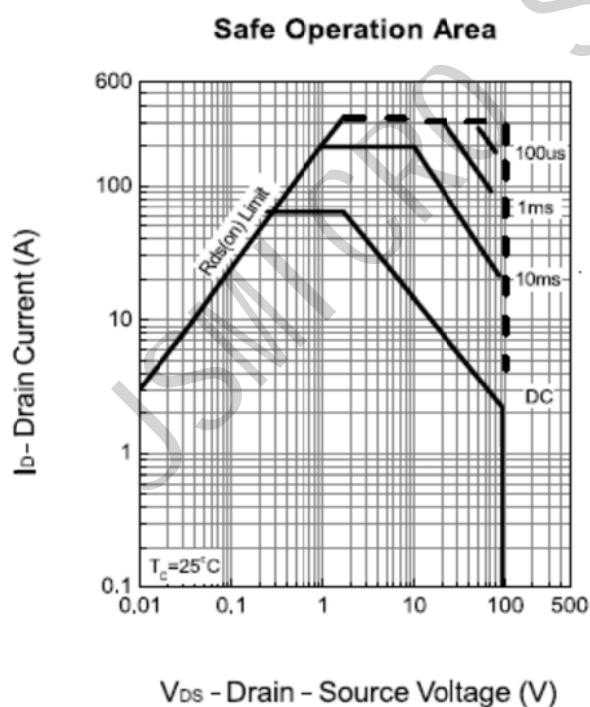
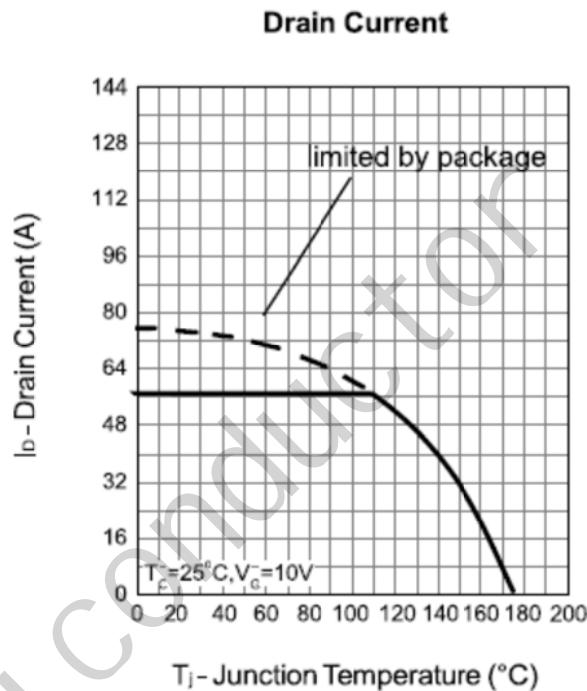
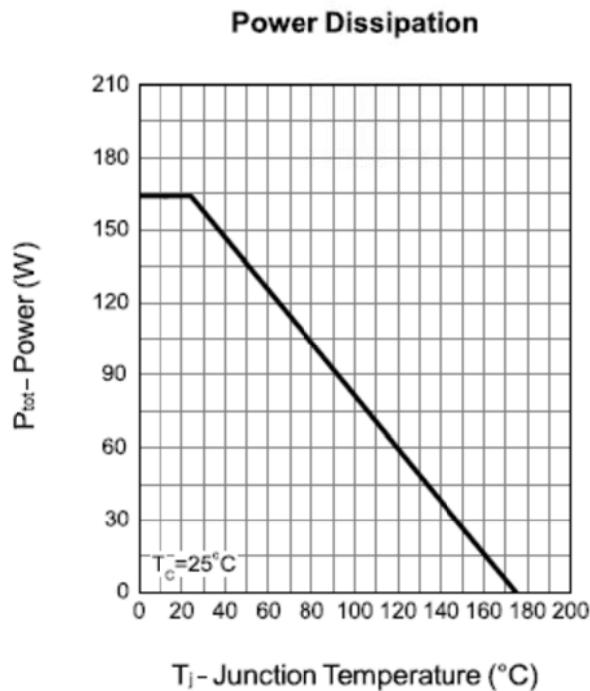
3: Package limitation current is 55A.

4: Repetitive rating, pulse width limited by max junction temperature.

5: Starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $I_{AS} = 30\text{A}$.

Typical Characteristics
Output Characteristics

Drain-Source On Resistance

Drain-Source On Resistance

Gate Threshold Voltage


Typical Characteristics (Continued)
Drain-Source On Resistance

Source-Drain Diode Forward

Capacitance

Gate Charge


Typical Characteristics (Continued)


外形尺寸图 / Package Dimensions

TO-263

Unit: mm

